Gallium Nitride 28V 220W, RF Power Transistor

Description

The NX4020H is a 200W 28V, GaN HEMT, designed for multiple applications with frequencies up to 3.2GHz.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

It is also the dual-path version of single ended NU4011H.

•Typical performance (on Innogration narrow band fixture with device soldered)

V_{DD}=28V I_{DQ}=1400mA, CW.

Frequency(MHz)	Gp (dB)	P _{sat} (W)	Efficiency (%)
1300	19	200	65



Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically –5 V
- 2. Turn on VDS to nominal supply voltage (28V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances
 (RoHS) Directive 2002/95/EC

Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings (Not simultaneous, TC = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	150	Vdc
GateSource Voltage	V _{GS}	-10,+2	Vdc
Operating Voltage	Vdd	40	Vdc
Maximum Forward Gate Current	Igmax	49	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	Tc	+150	°C
Operating Junction Temperature(See note 1)	۲J	+200	°C
Total Device Power Dissipation (Derated above 25°C, see note 2)	Pdiss	205	W

1. Continuous operation at maximum junction temperature will affect MTTF

2. Bias Conditions should also satisfy the following expression: Pdiss < (Tj – Tc) / RJC and Tc = Tcase

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Pa la pa	0.0	C/W
T_{C} = 85°C, T_{J} =200°C, DC Power Dissipation(See note 1)	Rejc-dc	0.9	

R0JC-DC is tested at only DC condition, it is related to the highest thermal resistor value among all test conditions. It might be differently lower in different RF operation conditions like CW signal ,pulsed RF signal etc.

Table 3. Electrical Characteristics (Tc = $25^{\circ}C$ unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	V _{GS} =-8V; I _{DS} =49mA	V _{DSS}	150			V
Gate Threshold Voltage	V _{DS} = 28V, I _D =49mA	V _{GS} (th)		-2.7		V
Gate Quiescent Voltage	V _{DS} =28V, I _{DS} =200mA, Measured in Functional Test	V _{GS(Q)}		-2.45		V

Functional Tests (In Innogration narrow band Test Fixture, 50 ohm system) :V_{DD} = 28 Vdc, I_{DQ} = 1400 mA, f = 1300 MHz, CW

Characteristic	Symbol	Min	Тур	Max	Unit
Power Gain @ P _{sat}	Gp		19		dB
Drain Efficiency @ P _{sat}	Eff		65		%
Saturated Power	P _{sat}		200		W
Input Return Loss	IRL		-7		dB
Mismatch stress at all phases (Device no damage)	VSWR		10:1		Ψ

Package Outline

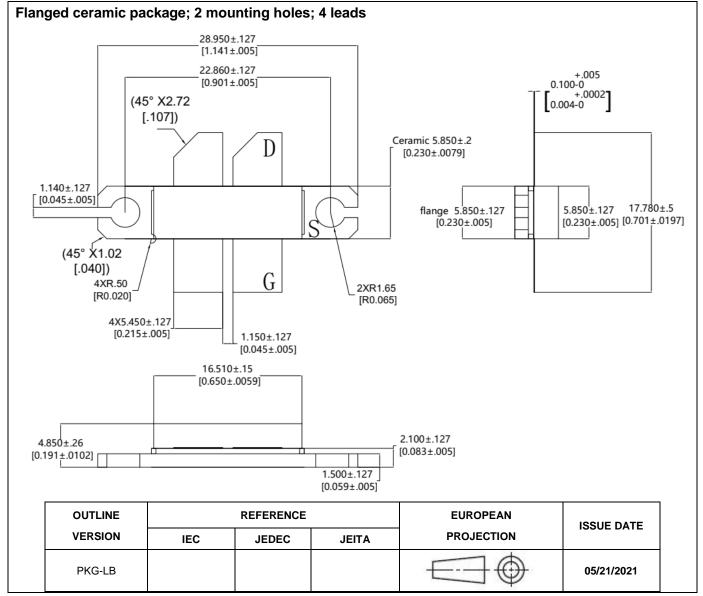


Figure 1. Package Outline PKG-LB(LBB)

Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2018/10/12	V1.0	Preliminary datasheet creation
2021/5/21	V1.1	Package outline update

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